

## FEATURES

- High power output
- Standard 3-lead TO-39 package
- Chip size .050 x .050 inches
- Case isolated

Dimensions are nominal values in inches unless otherwise specified.



## ELECTRO-OPTICAL CHARACTERISTICS AT 25°C

PARAMETERS	TEST CONDITIONS	MIN	TYP	MAX	UNITS
Total Power Output, $P_o$	$I_F = 300\text{mA}$	45	55		mW
Peak Emission Wavelength, $\lambda_p$	$I_F = 50\text{mA}$	462	470	475	nm
Spectral Bandwidth at 50%, $\Delta\lambda$			40		nm
Half Intensity Beam Angle, $\theta$				110	
Forward Voltage, $V_F$	$I_F = 300\text{mA}$		3.6	4	Volts
Reverse Breakdown Voltage, $V_R$	$I_R = 10\mu\text{A}$	2	5		Volts
Rise and Fall Time, $t_r, t_f$	$I_F = 50\text{mA}$		175		nsec

## ABSOLUTE MAXIMUM RATINGS AT 25°C CASE

Power Dissipation <sup>1</sup>	1000mW
Continuous Forward Current <sup>1</sup>	300mA
Reverse Voltage	2V
Lead Soldering Temperature (1/16" from case for 10sec)	260°C

<sup>1</sup> Derate per appropriate thermal dissipation value above 25°C.

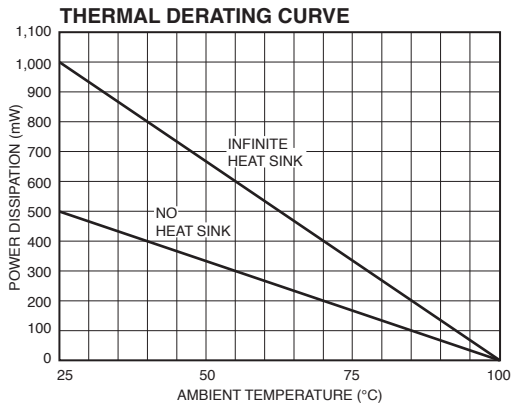
## THERMAL PARAMETERS

Storage and Operating Temperature Range	-40°C TO 100°C
Maximum Junction Temperature	100°C
Thermal Dissipation Junction-Case	75°C/W Typical
Thermal Dissipation Junction-Air	145°C/W Typical

<sup>1</sup> Derate per appropriate thermal dissipation value above 25°C.

Class 1 ESD sensitive. Observe appropriate precautions during handling.

MAXIMUM RATINGS



TYPICAL CHARACTERISTICS

